

484 - 532

SCR

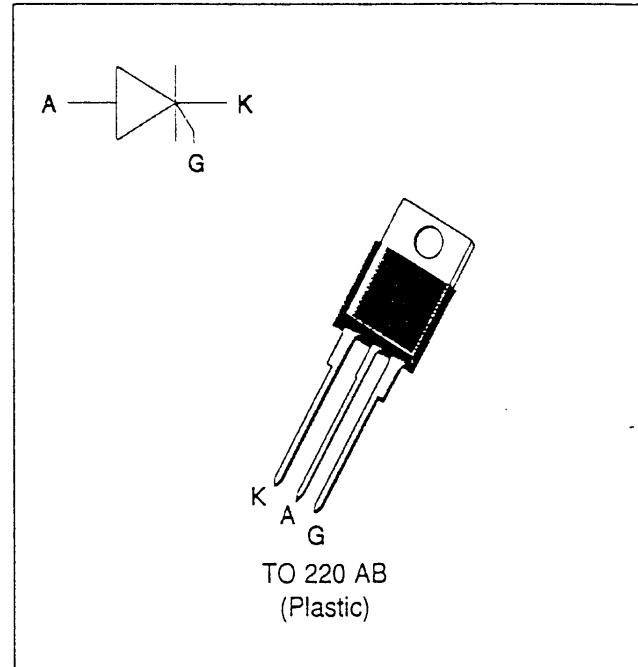
## FEATURES

- HIGH SURGE CAPABILITY
- HIGH ON-STATE CURRENT
- HIGH STABILITY AND RELIABILITY
- TXN Serie :  
INSULATED VOLTAGE = 2500V(RMS)  
(UL RECOGNIZED : E81734)

## DESCRIPTION

The TYN/TXN 0512 ---> TYN/TXN 1012 Family of Silicon Controlled Rectifiers uses a high performance glass passivated technology.

This general purpose Family of Silicon Controlled Rectifiers is designed for power supplies up to 400Hz on resistive or inductive load.



## ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit	
$I_T(\text{RMS})$	RMS on-state current (180° conduction angle)	TXN TYN	$T_c=80^\circ\text{C}$ $T_c=90^\circ\text{C}$	12	A
$I_T(\text{AV})$	Average on-state current (180° conduction angle, single phase circuit)	TXN TYN	$T_c=80^\circ\text{C}$ $T_c=90^\circ\text{C}$	8	A
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = 25°C)		$t_p=8.3 \text{ ms}$	125	A
			$t_p=10 \text{ ms}$	120	
$I_{2t}$	$I_{2t}$ value		$t_p=10 \text{ ms}$	$A^2\text{s}$	
$dI/dt$	Critical rate of rise of on-state current Gate supply : $I_G = 150 \text{ mA}$ $dI_G/dt = 1 \text{ A}/\mu\text{s}$		100	$\text{A}/\mu\text{s}$	
$T_{stg}$ $T_j$	Storage and operating junction temperature range		- 40 to + 150 - 40 to + 125	$^\circ\text{C}$	
$T_I$	Maximum lead temperature for soldering during 10 s at 4.5 mm from case		230	$^\circ\text{C}$	

Symbol	Parameter	TYN/TXN							Unit
		0512	112	212	412	612	812	1012	
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltage $T_j = 125^\circ\text{C}$	50	100	200	400	600	800	1000	V

## THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R <sub>th</sub> (j-a)	Junction to ambient	60	°C/W
R <sub>th</sub> (j-c) DC	Junction to case for DC	TXN	3.5
		TYN	2.5

## GATE CHARACTERISTICS (maximum values)

P<sub>G</sub> (AV) = 1W P<sub>GM</sub> = 40W (tp = 20 μs) I<sub>FGM</sub> = 4A (tp = 20 μs) V<sub>FGM</sub> = 16V (tp = 20 μs) V<sub>RGM</sub> = 5 V.

## ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions		Value	Unit
I <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	MAX	15
V <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	MAX	1.5
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3kΩ	T <sub>j</sub> = 125°C	MIN	0.2
t <sub>gt</sub>	V <sub>D</sub> =V <sub>DRM</sub> I <sub>G</sub> = 90mA dI <sub>G</sub> /dt = 0.8A/μs	T <sub>j</sub> =25°C	TYP	2
I <sub>L</sub>	I <sub>G</sub> = 1.2 I <sub>GT</sub>	T <sub>j</sub> =25°C	TYP	50
I <sub>H</sub>	I <sub>T</sub> = 100mA gate open	T <sub>j</sub> =25°C	MAX	30
V <sub>TM</sub>	I <sub>TM</sub> = 24A tp= 380μs	T <sub>j</sub> =25°C	MAX	1.6
IDRM IRRM	V <sub>DRM</sub> Rated V <sub>RRM</sub> Rated	T <sub>j</sub> =25°C	MAX	0.01
		T <sub>j</sub> = 125°C		3
dV/dt	Linear slope up to V <sub>D</sub> =67%V <sub>DRM</sub> gate open	T <sub>j</sub> = 125°C	MIN	200
T <sub>q</sub>	V <sub>D</sub> =67%V <sub>DRM</sub> I <sub>TM</sub> = 24A V <sub>R</sub> = 25V dI <sub>TM</sub> /dt=30 A/μs dV <sub>D</sub> /dt= 50V/μs	T <sub>j</sub> = 125°C	TYP	70

Fig.1 : Maximum average power dissipation versus average on-state current (TXN).

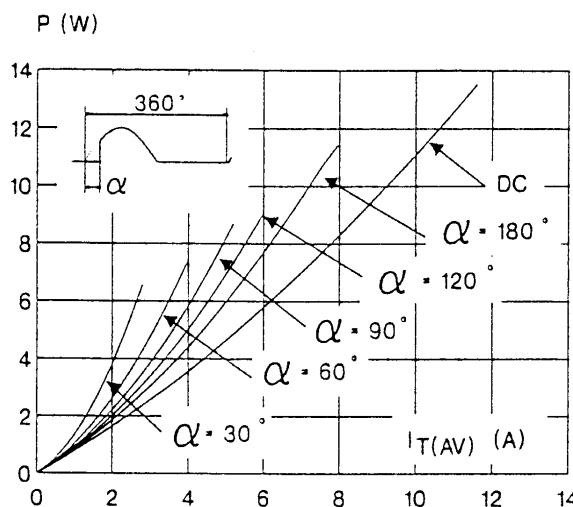


Fig.3 : Maximum average power dissipation versus average on-state current (TYN).

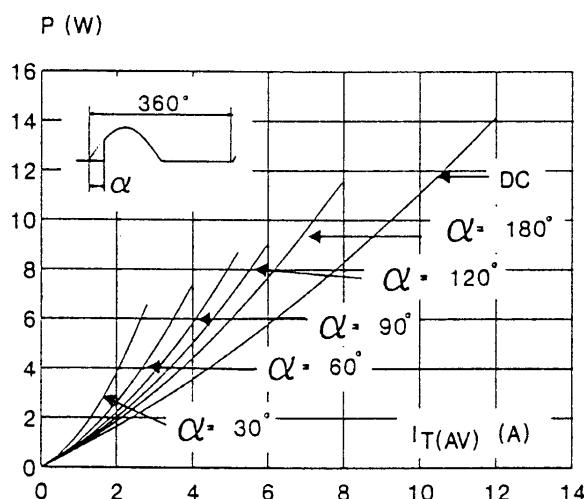


Fig.5 : Average on-state current versus case temperature (TXN).

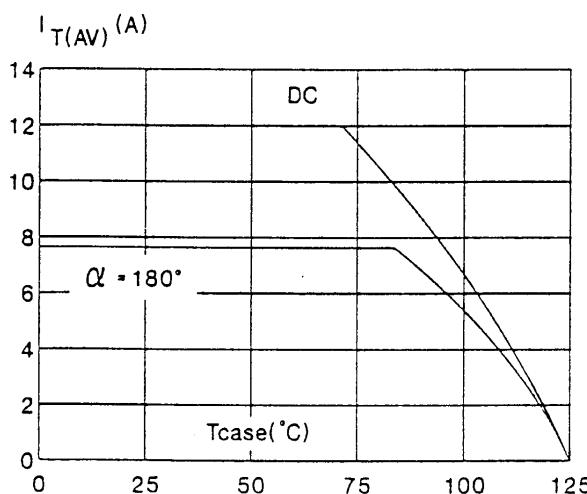


Fig.2 : Correlation between maximum average power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact (TXN).

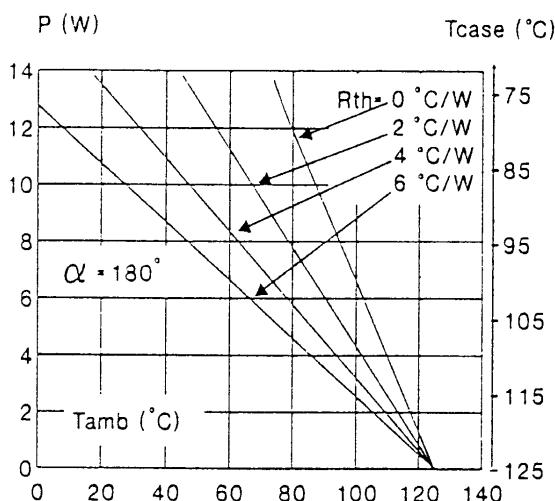


Fig.4 : Correlation between maximum average power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact (TYN).

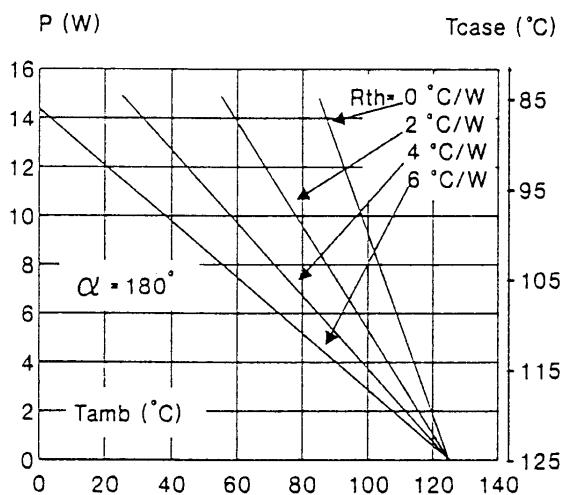
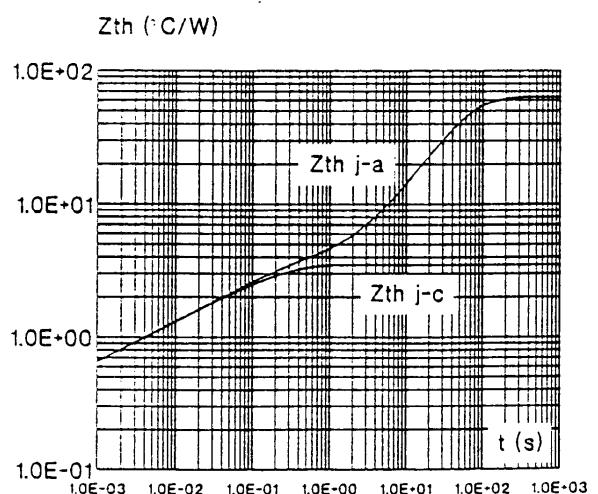


Fig.6 : Thermal transient impedance junction to ambient versus pulse duration (TXN).



# TXN/TYN 0512 ---> TXN/TYN 1012

Fig.7 : Average on-state current versus case temperature (TYN).

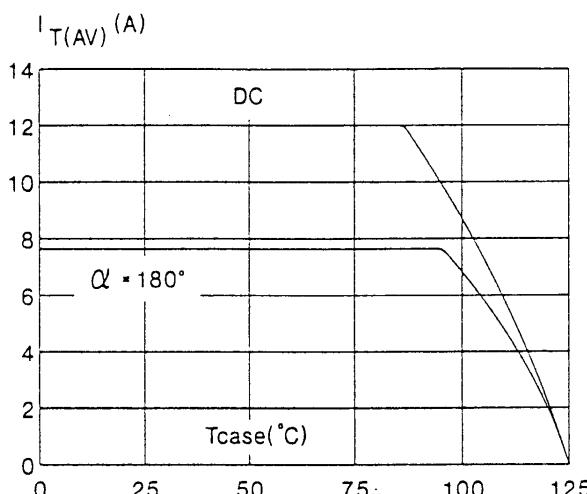


Fig.9 : Relative variation of gate trigger current versus junction temperature.

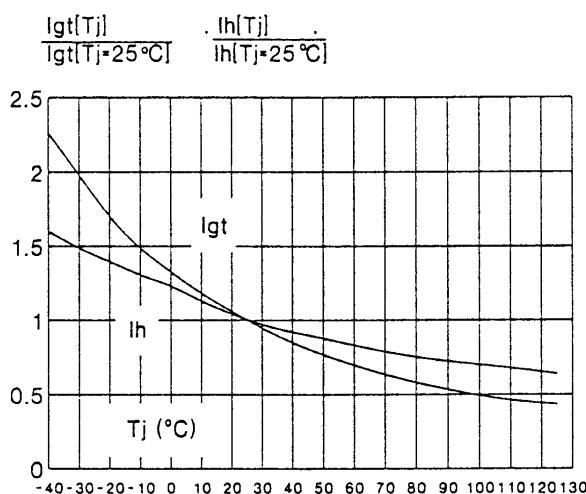


Fig.11 : Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10$  ms, and corresponding value of  $I^2t$ .

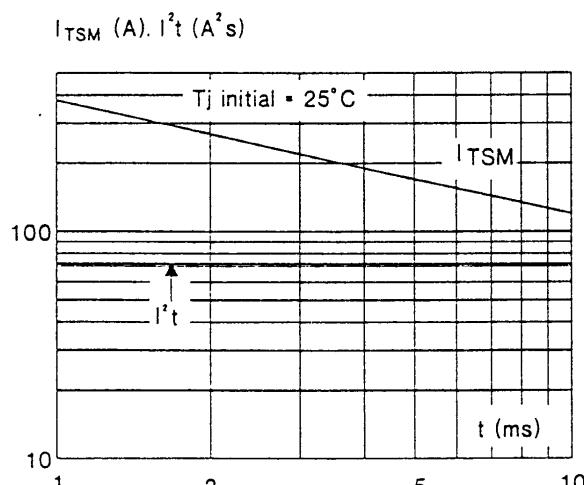


Fig.8 : Thermal transient impedance junction to ambient versus pulse duration (TYN).

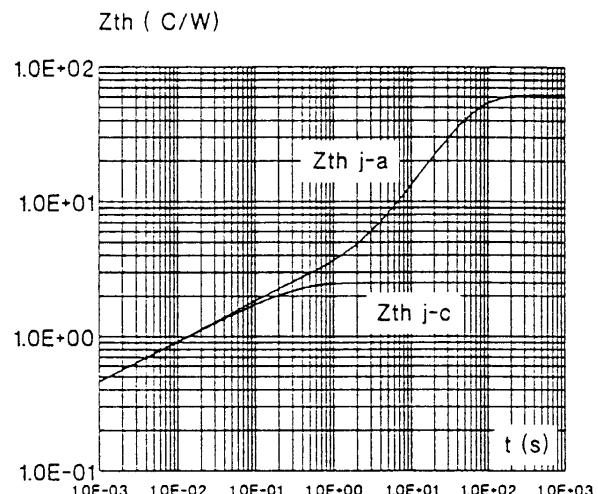


Fig.10 : Non repetitive surge peak on-state current versus number of cycles.

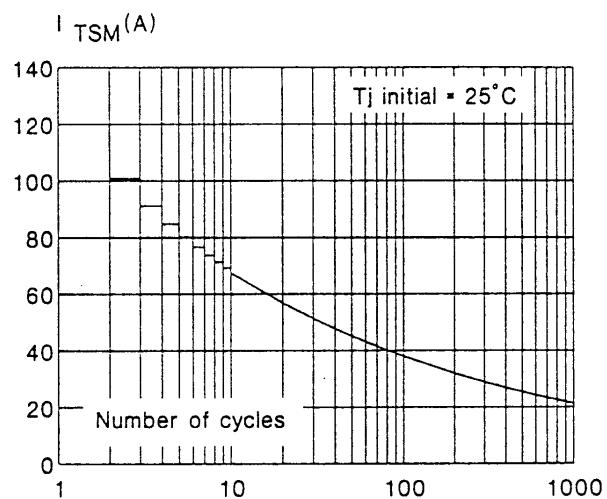
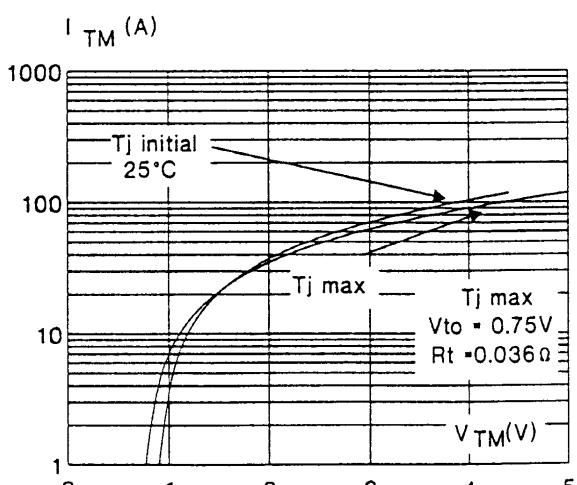
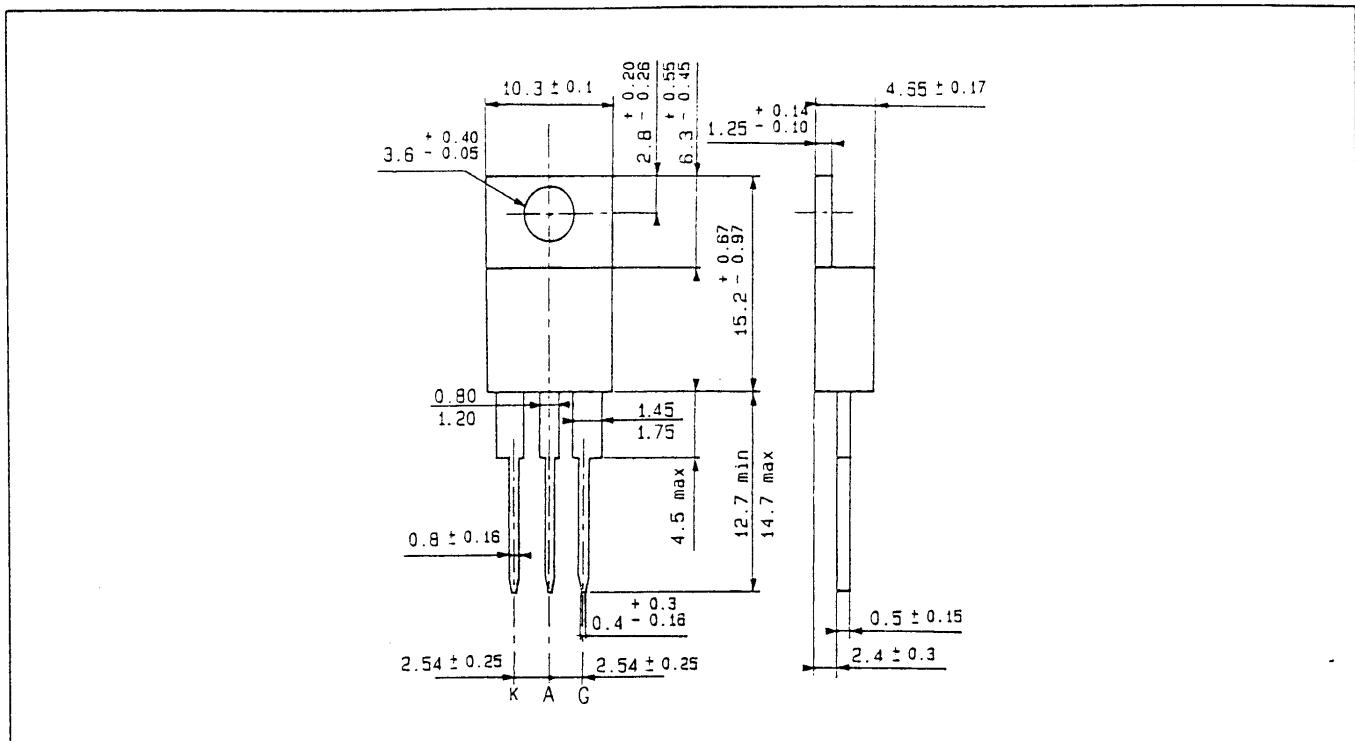


Fig.12 : On-state characteristics (maximum values).



## PACKAGE MECHANICAL DATA (in millimeters)

TO 220 AB Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g

Polarity : N A

Stud torque : N A

PCN DSG/DA/9501

ASSEMBLY CAPACITY EXTENSION : Insulated Triacs (BTA &amp; TXDV series)

**WHY THIS CHANGE**

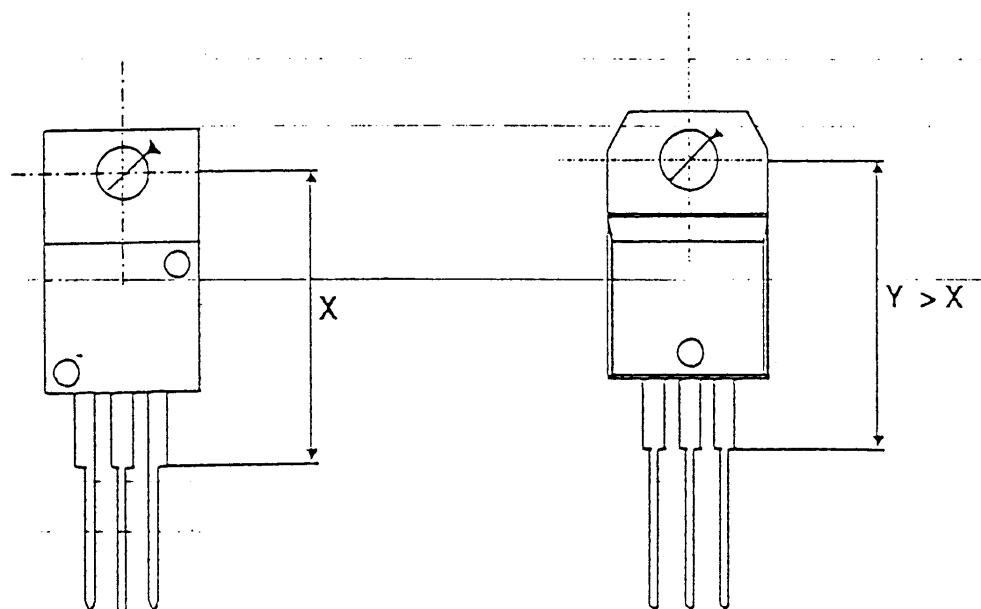
The growing success of our TO220 SCR&Triacs leads us to increase our assembly capacity. All additionnal assembly modules will use a new TO220 package in order to rationalize with all TO220 from the company (Transistors ; Rectifiers ; V-Reg...)

The first step was to move all SCR on this new package (TYN, TYP and TXN devices). This transfer has been completed in October 1995.

The second step will be to move insulated TO220 Triacs (i.e. BTA & TXDV series).

**WHAT IS THE CHANGE**

The change described in this PCN is only dealing with the package outlines. The main modification is the following :

*Stand Off Dimension**Current**New*

The impact for the customer can be : Distance from the hole to the PC board is increased by 0.7mm typical measured value (0.027 Inch typ.).

Minor changes are : Packages outlines (see Drawing hereattached) and Marking (Laser instead of ink)

PRODUCT CHANGE NOTIFICATION : Insulated TO220 Triacs

HOW

Qualification samples and qualification report are available on request.

WHEN

We will progressively switch BTA and TXDV series to this new package.

The schedule will be the following :

January 1st 1996	from 16Amps to 24Amps BTAs 12Amps TXDVs
August 1st 1996	12Amps BTAs & 10Amps Snubberless BTAs 8Amps TXDVs

See Appendix 3 for the complete list of devices according to the above planning

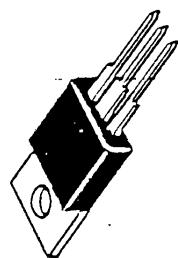
Remark :

The traceability will be done with a sticker mentioning "New Package" on each shipment box during the transition period (move from the current to the new package).

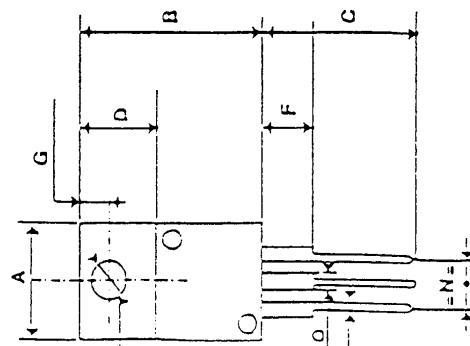
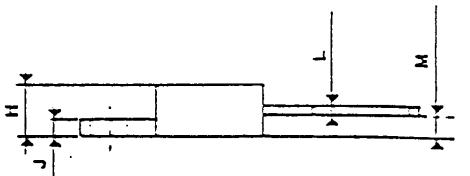
Appendix 2 : Package Outline Dimension

## APPENDIX 2 : PACKAGE OUTLINE DIMENSION

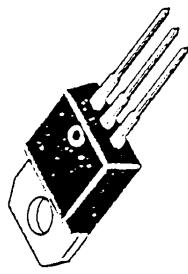
TO220AB  
OLD



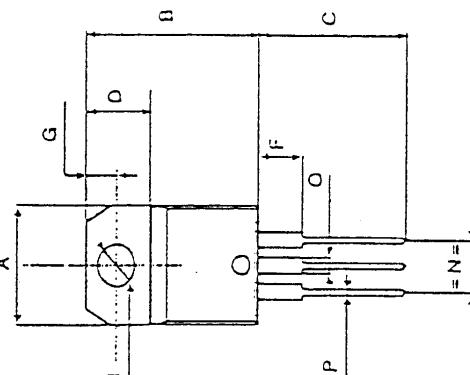
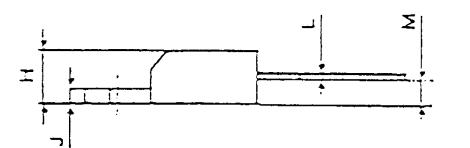
REF.	DIMENSIONS		
	Millimeters	Inches	Millimeters
A	10.20	0.401	0.413
B	14.23	0.560	0.625
C	12.70	0.500	0.579
D	5.85	0.230	0.270
F	4.50		0.178
G	2.54	0.100	0.119
H	4.48	0.182	0.190
I	3.55	0.140	0.158
J	1.15	0.045	0.055
L	0.35	0.013	0.026
M	2.10	0.082	0.107
N	4.58	0.18	0.22
O	0.80	0.031	0.048
P	0.64	0.025	0.038



TO220AB  
NEW



REF.	DIMENSIONS		
	Millimeters	Millimeters	Inches
A	10.00	10.40	0.393
B	15.20	15.90	0.598
C	13.00	14.00	0.511
D	6.20	6.60	0.244
F	3.50	4.20	0.137
G	2.65	2.95	0.104
H	4.40	4.60	0.173
I	3.75	3.85	0.147
J	1.23	1.32	0.048
L	0.49	0.70	0.027
M	2.40	2.72	0.094
N	4.80	5.40	0.188
O	1.14	1.70	0.044
P	0.61	0.88	0.034



Excellence in Power Processing and Protection

